

# NSM11156DW6T1G

## Dual PNP Transistors

### General Purpose PNP Transistor and PNP Transistor with Monolithic Bias Network

NSM11156DW6T1G contains a single PNP transistor and a monolithic bias network PNP transistor with two resistors; a series base resistor and a base-emitter resistor. This device is designed to replace multiple transistors and resistors on customer boards by integrating these components into a single device. NSM11156DW6T1G is housed in a SC-88/SOT-363 package which is ideal for low power surface mount applications in space constrained applications.

#### Features

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- Q1: PNP BRT, R1 = R2 = 10 k
- Q2: PNP
- This is a Pb-Free Device

#### Applications

- Logic Switching
- Amplification
- Driver Circuits
- Interface Circuits

#### MAXIMUM RATINGS

(T<sub>A</sub> = 25°C unless otherwise noted)

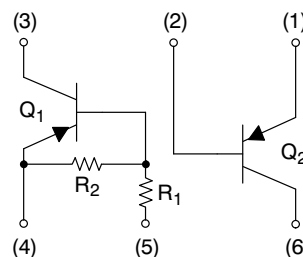
Rating - Q1 (PNP BRT)	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-50	Vdc
Collector-Emitter Voltage	V <sub>CEO</sub>	-50	Vdc
Collector Current	I <sub>C</sub>	-100	mAdc
Rating - Q2 (PNP)	Symbol	Value	Unit
Collector - Base Voltage	V <sub>(BR)CBO</sub>	-80	Vdc
Collector - Emitter Voltage	V <sub>(BR)CEO</sub>	-65	Vdc
Emitter - Base Voltage	V <sub>(BR)EBO</sub>	-5.0	Vdc
Collector Current - Continuous	I <sub>C</sub>	-100	mAdc

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



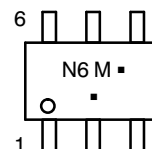
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SC-88/SOT-363  
CASE 419B  
STYLE 1

#### MARKING DIAGRAM



N6 = Device Code  
M = Date Code\*  
▪ = Pb-Free Package  
(Note: Microdot may be in either location)

\*Date Code orientation and/or position may vary depending upon manufacturing location.

#### ORDERING INFORMATION

Device	Package	Shipping†
NSM11156DW6T1G	SC-88 (Pb-Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# NSM11156DW6T1G

## THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	180 (Note 1) 1.44 (Note 1)	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	692 (Note 1)	$^\circ\text{C/W}$
Characteristic (Both Junctions Heated)	Symbol	Max	Unit
Total Device Dissipation, $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	230 1.83	mW mW/ $^\circ\text{C}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	544	$^\circ\text{C/W}$
Junction and Storage Temperature	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

1. FR-4 @ Minimum Pad of 1.45 mm<sup>2</sup>, 1 oz Cu.

## ELECTRICAL CHARACTERISTICS - Q1 (PNP BRT) ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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### OFF CHARACTERISTICS

Collector-Base Cutoff Current ( $V_{CB} = -50\text{ V}, I_E = 0$ )	$I_{CBO}$	-	-	-100	nAdc
Collector-Emitter Cutoff Current ( $V_{CE} = -50\text{ V}, I_B = 0$ )	$I_{CEO}$	-	-	-500	nAdc
Emitter-Base Cutoff Current ( $V_{EB} = -6.0\text{ V}, I_C = 0$ )	$I_{EBO}$	-	-	-0.5	mAdc
Collector-Base Breakdown Voltage ( $I_C = -10\ \mu\text{A}, I_E = 0$ )	$V_{(BR)CBO}$	-50	-	-	Vdc
Collector-Emitter Breakdown Voltage (Note 2) ( $I_C = -2.0\text{ mA}, I_B = 0$ )	$V_{(BR)CEO}$	-50	-	-	Vdc

### ON CHARACTERISTICS (Note 2)

DC Current Gain ( $V_{CE} = -10\text{ V}, I_C = -5.0\text{ mA}$ )	$h_{FE}$	35	60	-	
Collector-Emitter Saturation Voltage ( $I_C = -10\text{ mA}, I_B = -0.3\text{ mA}$ )	$V_{CE(sat)}$	-	-	-0.25	Vdc
Output Voltage (on) ( $V_{CC} = -5.0\text{ V}, V_B = -2.5\text{ V}, R_L = 1.0\text{ k}\Omega$ )	$V_{OL}$	-	-	-0.2	Vdc
Output Voltage (off) ( $V_{CC} = -5.0\text{ V}, V_B = -0.5\text{ V}, R_L = 1.0\text{ k}\Omega$ )	$V_{OH}$	-4.9	-	-	Vdc
Input Resistor	R1	7.0	10	13	k $\Omega$
Resistor Ratio	R1/R2	0.8	1.0	1.2	

2. Pulse Test: Pulse Width < 300  $\mu\text{s}$ , Duty Cycle < 2.0%

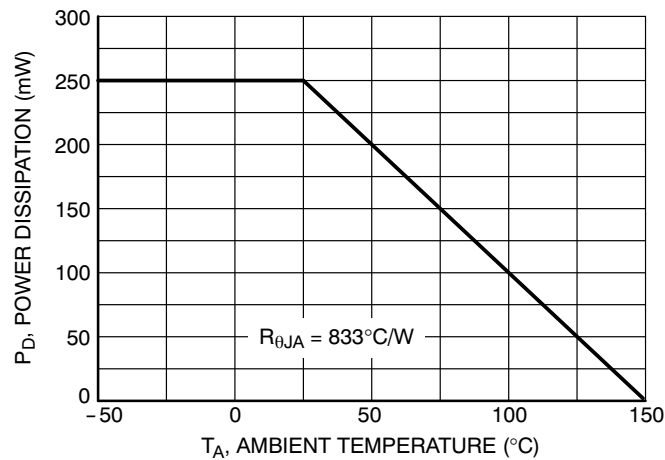
# NSM11156DW6T1G

## ELECTRICAL CHARACTERISTICS - Q2 (PNP) ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>					
Collector - Emitter Breakdown Voltage ( $I_C = -10\text{ mA}$ )	$V_{(BR)CEO}$	-65	-	-	V
Collector - Emitter Breakdown Voltage ( $I_C = -10\ \mu\text{A}$ , $V_{EB} = 0$ )	$V_{(BR)CES}$	-80	-	-	V
Collector - Base Breakdown Voltage ( $I_C = -10\ \mu\text{A}$ )	$V_{(BR)CBO}$	-80	-	-	V
Emitter - Base Breakdown Voltage ( $I_E = -1.0\ \mu\text{A}$ )	$V_{(BR)EBO}$	-5.0	-	-	V
Collector Cutoff Current ( $V_{CB} = -30\text{ V}$ ) ( $V_{CB} = -30\text{ V}$ , $T_A = 150^\circ\text{C}$ )	$I_{CBO}$	-	-	-15 -4.0	nA $\mu\text{A}$

## ON CHARACTERISTICS

DC Current Gain ( $I_C = -10\ \mu\text{A}$ , $V_{CE} = -5.0\text{ V}$ ) ( $I_C = -2.0\text{ mA}$ , $V_{CE} = -5.0\text{ V}$ )	$h_{FE}$	- 220	150 290	- 475	-
Collector - Emitter Saturation Voltage ( $I_C = -10\text{ mA}$ , $I_B = -0.5\text{ mA}$ ) ( $I_C = -100\text{ mA}$ , $I_B = -5.0\text{ mA}$ )	$V_{CE(sat)}$	- -	- -	-0.3 -0.65	V
Base - Emitter Saturation Voltage ( $I_C = -10\text{ mA}$ , $I_B = -0.5\text{ mA}$ ) ( $I_C = -100\text{ mA}$ , $I_B = -5.0\text{ mA}$ )	$V_{BE(sat)}$	- -	-0.7 -0.9	- -	V
Base - Emitter On Voltage ( $I_C = -2.0\text{ mA}$ , $V_{CE} = -5.0\text{ V}$ ) ( $I_C = -10\text{ mA}$ , $V_{CE} = -5.0\text{ V}$ )	$V_{BE(on)}$	-0.6 -	- -	-0.75 -0.82	V



**Figure 1. Derating Curve**

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

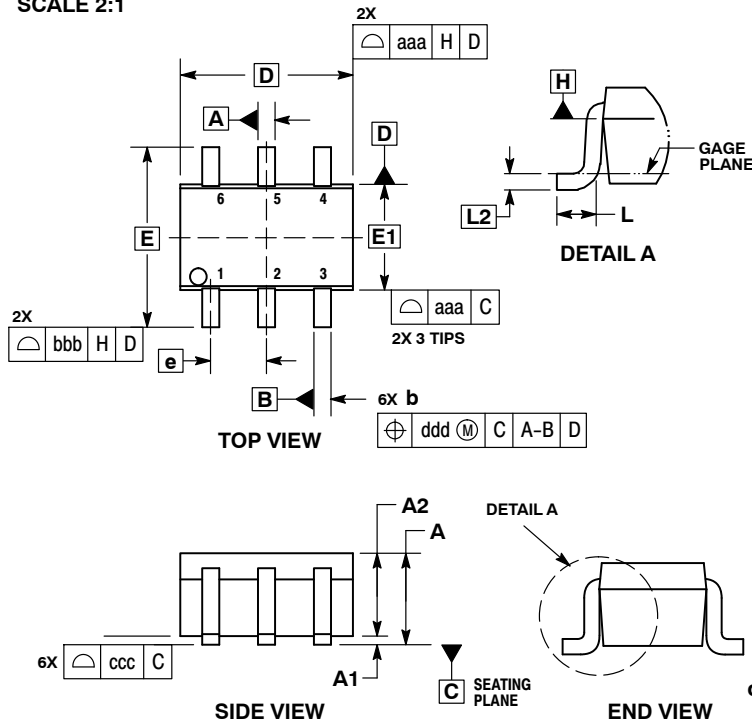
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1  
SCALE 2:1

SC-88/SC70-6/SOT-363  
CASE 419B-02  
ISSUE Y

DATE 11 DEC 2012

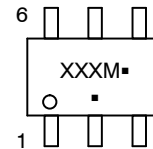


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSIONS  $D$  AND  $E1$  DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
4. DIMENSIONS  $D$  AND  $E1$  AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM  $H$ .
5. DATUMS  $A$  AND  $B$  ARE DETERMINED AT DATUM  $H$ .
6. DIMENSIONS  $b$  AND  $c$  APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
7. DIMENSION  $b$  DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION  $b$  AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	---	---	1.10	---	---	0.043
A1	0.00	---	0.10	0.000	---	0.004
A2	0.70	0.90	1.00	0.027	0.035	0.039
b	0.15	0.20	0.25	0.006	0.008	0.010
C	0.08	0.15	0.22	0.003	0.006	0.009
D	1.80	2.00	2.20	0.070	0.078	0.086
E	2.00	2.10	2.20	0.078	0.082	0.086
E1	1.15	1.25	1.35	0.045	0.049	0.053
e	0.65 BSC			0.026 BSC		
L	0.26	0.36	0.46	0.010	0.014	0.018
L2	0.15 BSC			0.006 BSC		
aaa	0.15			0.006		
bbb	0.30			0.012		
ccc	0.10			0.004		
ddd	0.10			0.004		

**GENERIC MARKING DIAGRAM\***



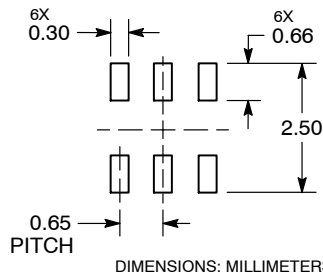
- XXX = Specific Device Code
- M = Date Code\*
- = Pb-Free Package

(Note: Microdot may be in either location)

\*Date Code orientation and/or position may vary depending upon manufacturing location.

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

**RECOMMENDED SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**STYLES ON PAGE 2**

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**SC-88/SC70-6/SOT-363**  
**CASE 419B-02**  
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<b>STYLE 1:</b> PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	<b>STYLE 2:</b> CANCELLED	<b>STYLE 3:</b> CANCELLED	<b>STYLE 4:</b> PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	<b>STYLE 5:</b> PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	<b>STYLE 6:</b> PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
<b>STYLE 7:</b> PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	<b>STYLE 8:</b> CANCELLED	<b>STYLE 9:</b> PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	<b>STYLE 10:</b> PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	<b>STYLE 11:</b> PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	<b>STYLE 12:</b> PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
<b>STYLE 13:</b> PIN 1. ANODE 2. N/C 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	<b>STYLE 14:</b> PIN 1. VREF 2. GND 3. GND 4. IOUT 5. VEN 6. VCC	<b>STYLE 15:</b> PIN 1. ANODE 1 2. ANODE 2 3. ANODE 3 4. CATHODE 3 5. CATHODE 2 6. CATHODE 1	<b>STYLE 16:</b> PIN 1. BASE 1 2. EMITTER 2 3. COLLECTOR 2 4. BASE 2 5. EMITTER 1 6. COLLECTOR 1	<b>STYLE 17:</b> PIN 1. BASE 1 2. EMITTER 1 3. COLLECTOR 2 4. BASE 2 5. EMITTER 2 6. COLLECTOR 1	<b>STYLE 18:</b> PIN 1. VIN1 2. VCC 3. VOUT2 4. VIN2 5. GND 6. VOUT1
<b>STYLE 19:</b> PIN 1. IOUT 2. GND 3. GND 4. V CC 5. V EN 6. V REF	<b>STYLE 20:</b> PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR	<b>STYLE 21:</b> PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. N/C 6. CATHODE 1	<b>STYLE 22:</b> PIN 1. D1 (i) 2. GND 3. D2 (i) 4. D2 (c) 5. VBUS 6. D1 (c)	<b>STYLE 23:</b> PIN 1. Vn 2. CH1 3. Vp 4. N/C 5. CH2 6. N/C	<b>STYLE 24:</b> PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
<b>STYLE 25:</b> PIN 1. BASE 1 2. CATHODE 3. COLLECTOR 2 4. BASE 2 5. EMITTER 6. COLLECTOR 1	<b>STYLE 26:</b> PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1	<b>STYLE 27:</b> PIN 1. BASE 2 2. BASE 1 3. COLLECTOR 1 4. EMITTER 1 5. EMITTER 2 6. COLLECTOR 2	<b>STYLE 28:</b> PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN	<b>STYLE 29:</b> PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE/ANODE 6. CATHODE	<b>STYLE 30:</b> PIN 1. SOURCE 1 2. DRAIN 2 3. DRAIN 2 4. SOURCE 2 5. GATE 1 6. DRAIN 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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